

ABSTRACT OF THE DISCLOSURE

A semiconductor device is disclosed, which
comprise a first semiconductor chip where a
semiconductor element is formed, a first connecting
5 terminal arranged on a semiconductor element formation
surface side in the first semiconductor chip and
connected electrically to the semiconductor element, a
conductive member buried in a through hole that goes
through the first semiconductor chip, a second
10 connecting terminal arranged on a back surface side of
the semiconductor element formation surface in the
first semiconductor chip, and connected electrically to
the semiconductor element via the conductive member, a
wiring substrate to which the first semiconductor chip
15 is mounted, and a third connecting terminal at least
portion of which is formed at a position corresponding
to one of the first connecting terminal and the second
connecting terminal, and which is electrically
connected to the one of the first connecting terminal
20 and the second connecting terminal.